

Part Number: 1700711212

Product Description : zSFP+ Stacked Ganged Assembly with Elastomeric Gasket, 2-by-12

with Inner Light Pipes, 480 Circuits

Status: Active

Series Number: 170071

Product Category: High-Speed I/O

Connectors

Documents & Resources

Drawings

Drawing 1700711212_sd.pdf

3D Models and Design Files

3D Model 1700711212_stp.zip

Electrical Model Document EE-170071-0001-001.pdf

S-Parameter Model SP-170426-1000-001.zip

Specifications

Application Specification AS-170071-0002-001.pdf
Product Specification PS-170071-0001-001.pdf
Test Summary TS-170071-0001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 44; 34; 33
China RoHS	<u> </u>
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2- 21
REACH SVHC	Not Contained per D(2024)4144-DC (27 June 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	170071
Description	zSFP+ Stacked Ganged Assembly with Elastomeric Gasket, 2-by-12 with Inner Light Pipes, 480 Circuits
Application	Module-to-Board
Component Type	Receptacle
Product Family	SFP+ and SFP Interconnect Solutions
Product Name	zSFP Plus,zSFP+
Туре	N/A
UPC	887191132877

Electrical

Current - Maximum per Contact	0.5A
Data Rate	28.0 Gbps
Shield Type	N/A
Shielded	Yes
Voltage - Maximum	30V AC

Physical

Circuits (Loaded)	480
Color - Resin	Black
Durability (mating cycles max)	100
Gender	Female
Lock to Mating Part	Yes

Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Matte Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	277.512/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Tray
Panel Mount	No
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	2.36mm
Pitch - Mating Interface	0.80mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	24
Temperature Range - Operating	-40° to +85°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A